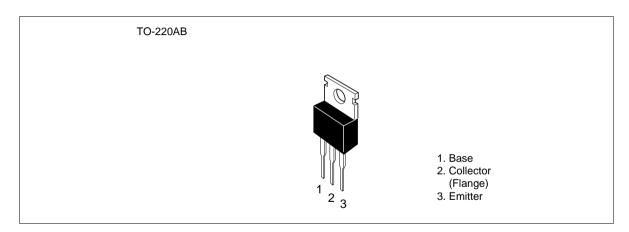
## Silicon PNP Triple Diffused

# **HITACHI**

#### **Application**

Low frequency power amplifier power switching complementary pair with 2SD476(K) and 2SD476A(K)

#### Outline



### **Absolute Maximum Ratings** $(Ta = 25^{\circ}C)$

		Ratings			
Item	Symbol	2SB566(K)	2SB566A(K)	Unit	
Collector to base voltage	$V_{CBO}$	-70	<del>-7</del> 0	V	
Collector to emitter voltage	V <sub>CEO</sub>	-50	<b>–</b> 60	V	
Emitter to base voltage	$V_{EBO}$	<b>-</b> 5	<b>-</b> 5	V	
Collector current	I <sub>c</sub>	-4	-4	Α	
Collector peak current	I <sub>C(peak)</sub>	-8	-8	А	
Collector power dissipation	P <sub>C</sub> *1	40	40	W	
Junction temperature	Tj	150	150	°C	
Storage temperature	Tstg	-55 to +150	-55 to +150	°C	
• •					

Note: 1. Value at  $T_c = 25$ °C.

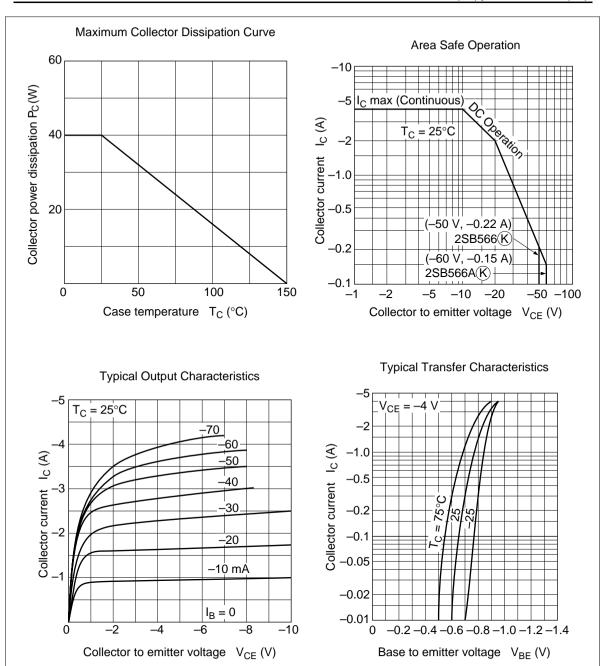


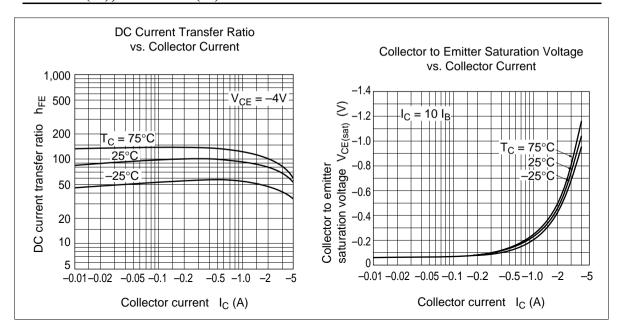
### **Electrical Characteristics** ( $Ta = 25^{\circ}C$ )

		2SB5	66(K)		2SB566A(K)				
Item	Symbol	Min	Тур	Max	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	-70	_	_	-70	_	_	V	$I_{\rm C} = -10 \; \mu \text{A}, \; I_{\rm E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	<b>–</b> 50	_	_	-60	_	_	V	$I_{\rm C} = -50$ mA, $R_{\rm BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	<b>-</b> 5	_	_	<b>-</b> 5	_	_	V	$I_{E} = -10 \mu\text{A},  I_{C} = 0$
Collector cutoff current	I <sub>CBO</sub>	_	_	-1	_	_	-1	μΑ	$V_{CB} = -50 \text{ V}, I_{E} = 0$
DC current tarnsfer ratio	h <sub>FE1</sub> *1	60		200	60	_	200		$V_{CE} = -4 \text{ V}, I_{C} = -1 \text{ A}$
	h <sub>FE2</sub>	35	_	_	35	_	_		$V_{CE} = -4 \text{ V}, I_{C} = -0.1 \text{ A}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	_	-1.0	_	_	-1.0	V	$I_{\rm C} = -2 \text{ A}, I_{\rm B} = -0.2 \text{ A}$
Base to emitter saturation voltage	$V_{BE(sat)}$	_	_	-1.2	_	_	-1.2	V	$I_{\rm C} = -2 \text{ A}, I_{\rm B} = -0.2 \text{ A}$
Gain bandwidth product	$f_{T}$	_	15	_	_	15	_	MHz	$V_{CE} = -4 \text{ V}, I_{C} = -0.5 \text{ A}$
Turn on time	t <sub>on</sub>	_	0.3	_	_	0.3	_	μs	$V_{cc} = -10.5 \text{ V}$
Turn off time	t <sub>off</sub>		3.0			3.0	_	μs	$I_{\rm C} = 10I_{\rm B1} = -10I_{\rm B2} =$
Storage time	t <sub>stg</sub>	_	2.5	_	_	2.5	_	μs	-0.5 A

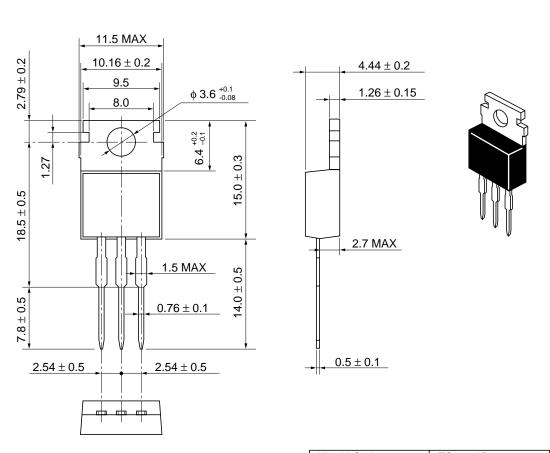
Note: 1. The 2SB566(K) and 2SB566A(K) are grouped by  $h_{\text{FE1}}$  as follows.

В	С
60 to 120	100 to 200





Unit: mm



Hitachi Code	TO-220AB
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	1.8 g

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